



Material Content Data Sheet



Sales Product Name		BSZ130N03LS G		Issued		29. August 2013		
MA#		MA000896770						
Package		PG-TSDSON-8-21		Weight*		36.66 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	0.531	1.45	1.45	14478	14478
leadframe	inorganic material	phosphorus	7723-14-0	0.002	0.01		65	
	non noble metal	zinc	7440-66-6	0.009	0.03		258	
	non noble metal	iron	7439-89-6	0.189	0.52		5166	
wire	non noble metal	copper	7440-50-8	7.689	20.97	21.53	209747	215236
	noble metal	gold	7440-57-5	0.086	0.24	0.24	2352	2352
encapsulation	organic material	carbon black	1333-86-4	0.039	0.11		1074	
	plastics	epoxy resin	-	2.027	5.53		55301	
	inorganic material	silicondioxide	60676-86-0	17.615	48.05	53.69	480528	536903
leadfinish	non noble metal	tin	7440-31-5	0.370	1.01	1.01	10095	10095
plating	noble metal	silver	7440-22-4	0.081	0.22	0.22	2204	2204
solder	non noble metal	tin	7440-31-5	0.042	0.11		1142	
	non noble metal	lead	7439-92-1	0.796	2.17	2.28	21703	22845
heat sink CLIP	inorganic material	phosphorus	7723-14-0	0.001	0.00		27	
	non noble metal	zinc	7440-66-6	0.004	0.01		107	
	non noble metal	iron	7439-89-6	0.078	0.21		2138	
	non noble metal	copper	7440-50-8	3.182	8.68	8.90	86796	89068
heatspreader	inorganic material	phosphorus	7723-14-0	0.001	0.00		32	
	non noble metal	zinc	7440-66-6	0.005	0.01		128	
	non noble metal	iron	7439-89-6	0.094	0.26		2564	
	non noble metal	copper	7440-50-8	3.816	10.41	10.68	104095	106819
*deviation	< 10%		Sum in total:			100.00		1000000

Important Remarks:

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